

Lecture 7: Lithography I

• Announcements:

↳ none

• Lecture Topics:

↳ Masks & alignment

↳ Lambda design rules

↳ Four main components of lithography

– Radiation source

– Mask

– Photoresist

– Exposure system

↳ Resolution

↳ Linewidth control

↳ Alignment accuracy

• Last Time:

• Go through the last lecture notes

• Emphasize:

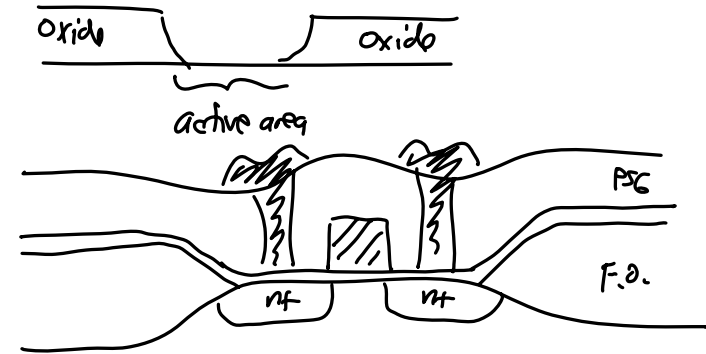
↳ Avoid high energy implant into photoresist, since too high an energy can heat the PR up and make it hard to remove

↳ Redo the oxide over active area regions after the threshold implant, since the implanted oxide is damaged - this is why the gate oxide is regrown

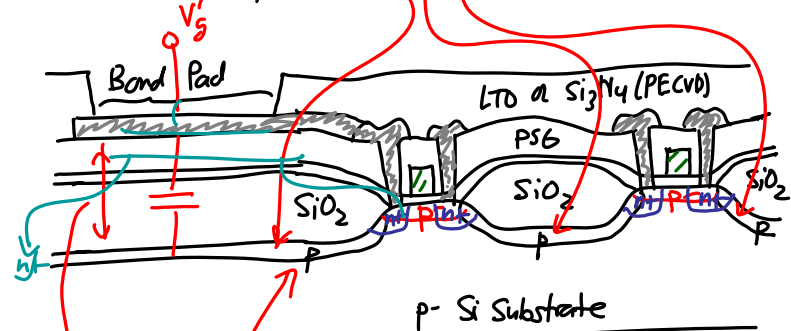
↳ p-type implant under the field oxide regions is there to prevent parasitic NMOS device under metal interconnect from turning on

↳ LOCOS bird's beak helps to reduce topography in going from thin to thick oxide regions

In Lab: Irradiation

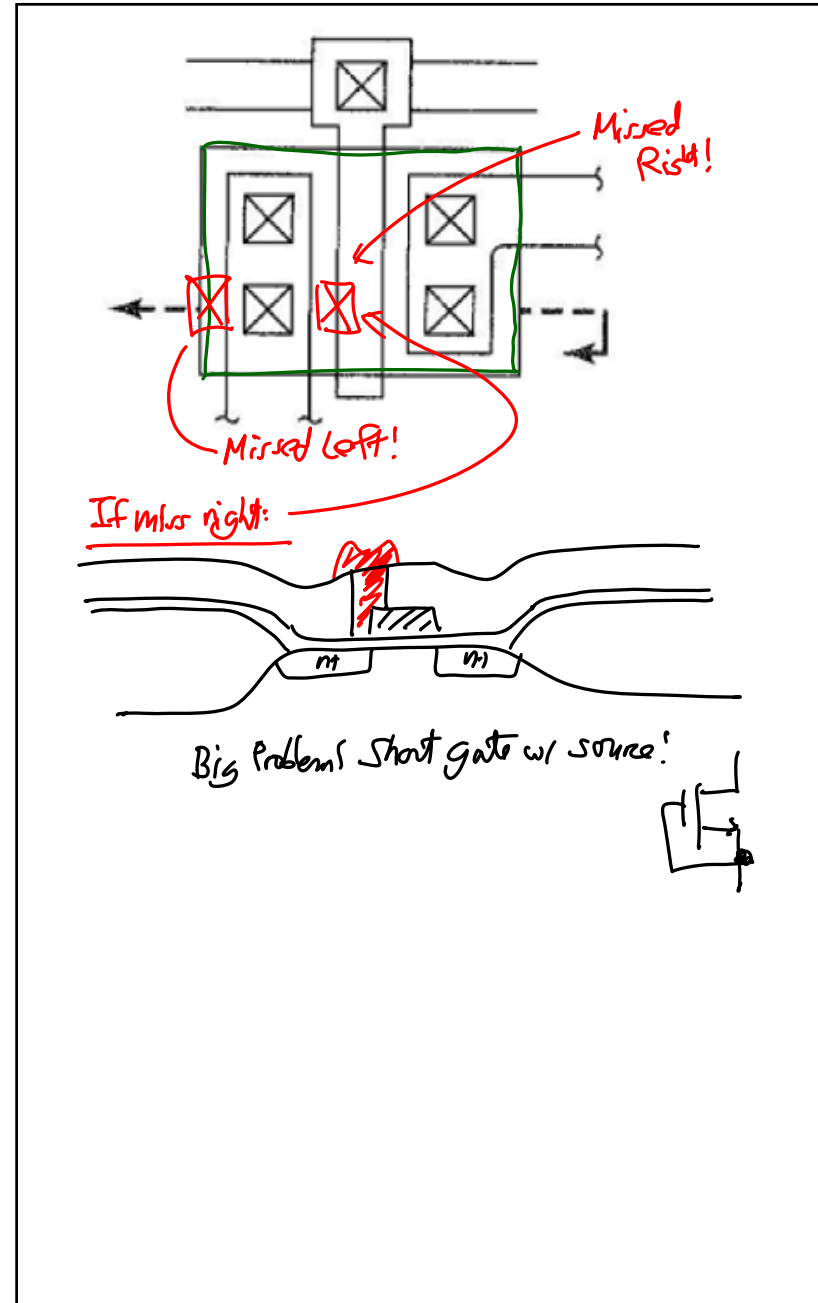
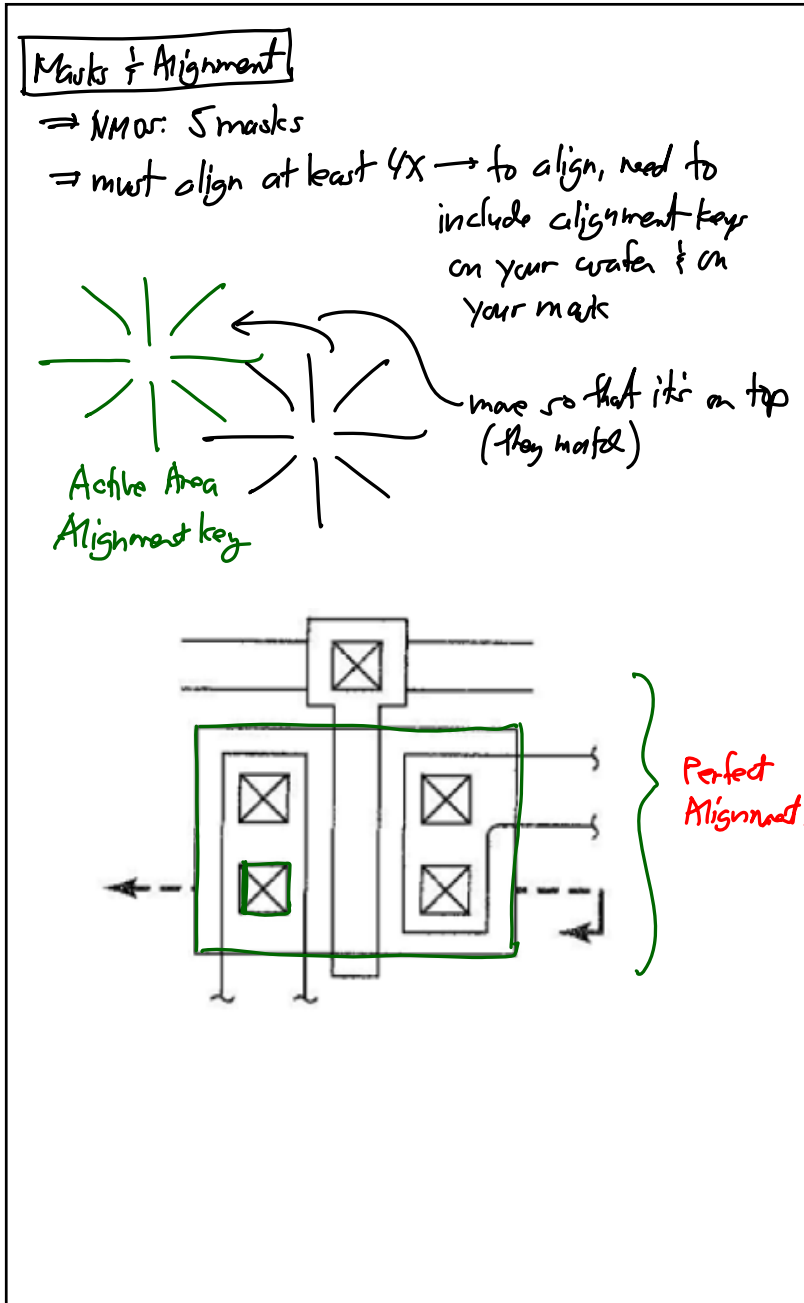


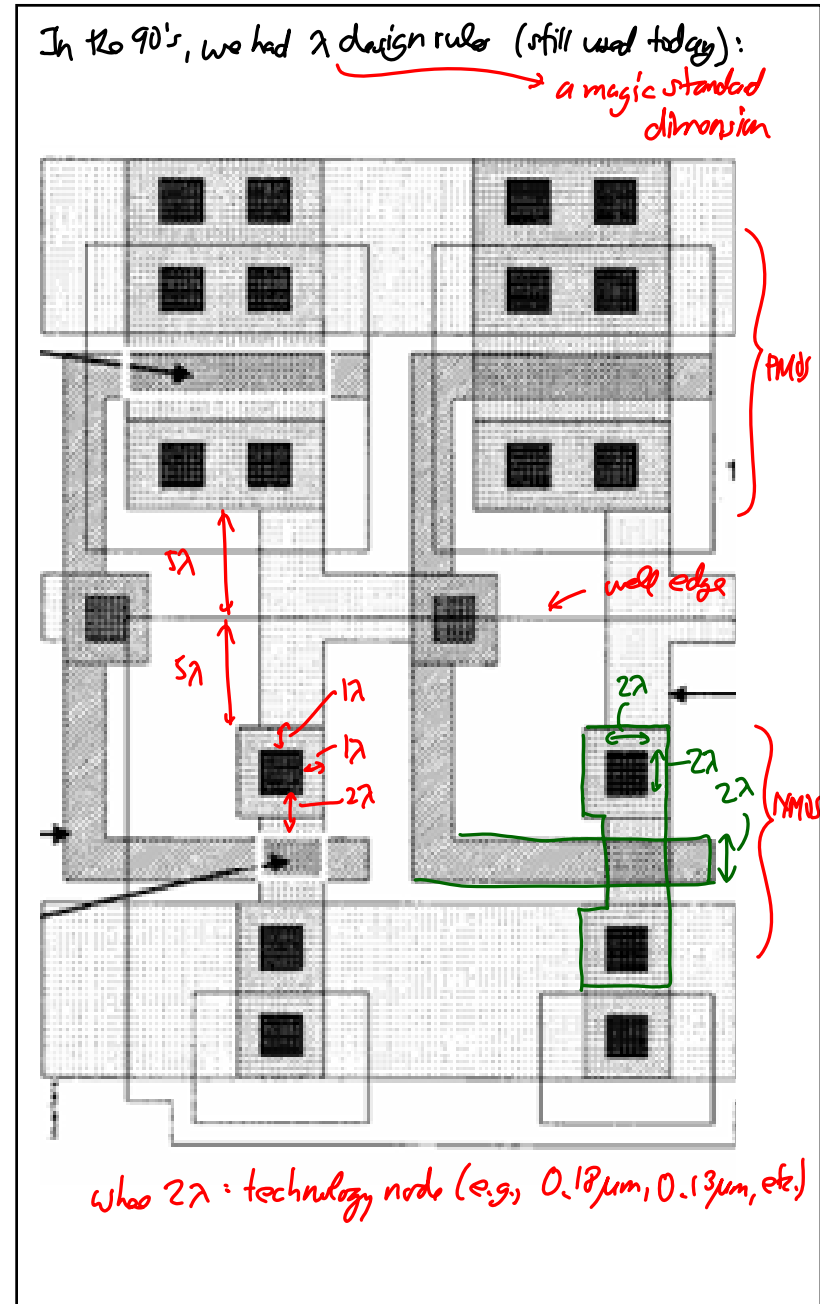
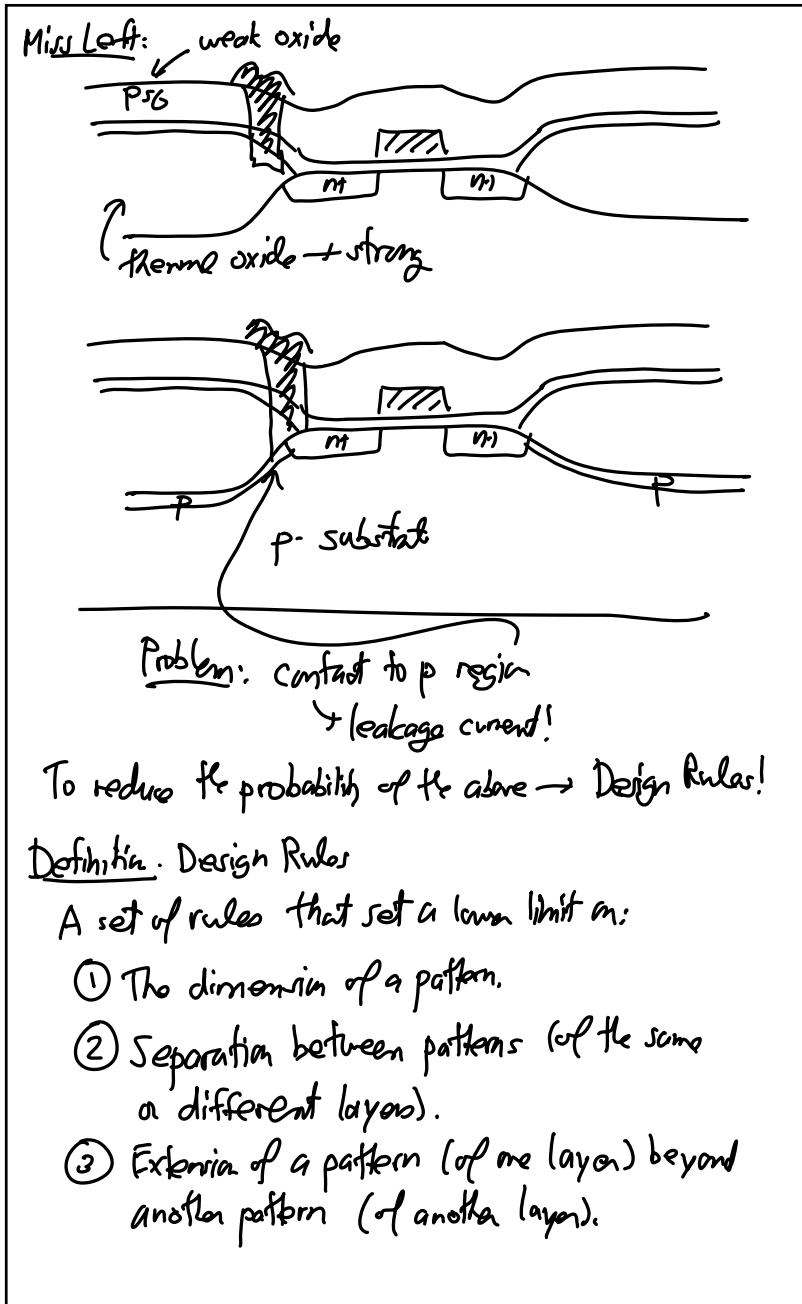
What's with the p regions here?



① Make F.O. thick → raises the V_t' of the parasitic NMOS device

② Implant p → raises the V_t' !





What determines these rules?

P_c ← gate poly
 ← minimum dimension of contact
 E_{AC} → Extension of Active Area (A) Beyond Contact (C)

P_c → limited by resolution of photolithography

E_{AC} = Alignment Error (layer-to-layer) $\sim 0.5\lambda$

- + Undercutting of Contact Hole (a size variation) → $0.3 - 0.5\lambda$
- + Encroachment of Active Region (key to Bird's book field oxide)
 (can be up to 1λ → this is why people today don't like COG (for $< 90\text{nm}$))

Which alignment key (a layer) to align to?

- Active Area (df)
- Gate Poly (cf)
- Contact (df)
- Metal (cf)
- Bond Pad Opening (df)

Lithography

→ method for massive patterning of features on a wafer → pattern billions of devices in just a few steps

Four Main Components: (that affect resolution)

I. Radiation Source
 II. Mask
 ← glass/quartz
 ← photoresist
 ← film to be patterned
 III. Photoresist
 IV. Exposure System